

Abstract of the Disclosure

A microprobe is manufactured by forming via hole on one edge portion of the silicon substrate, filling the via hole with the conductive layer, forming the conductive spring unit on the silicon substrate so as to be electrically connected to the conductive layer in the via hole, forming the conductive tip portion on the leading end of the spring unit, removing the silicon substrate under the spring unit using isotropic etching, thereby supporting the spring unit only on the portion adjacent to the via hole. The spring unit and the tip portion are formed only in the window of a PR. The microprobe has benefits in that a separation of signal between tip portions is easy and mechanical and electrical properties of the probe tip are good, since the probe is formed on the silicon substrate by using micro-processing. Also, since the pitch between the tip portions can be reduced, a semiconductor device with fine pitch pad can be tested. Furthermore, the uniformity of flatness of the probe tip portion can be improved.